Reference signs

- 100 p-MOS layer sequences
- 101 n-MOS layer sequences
- 102 layer sequences
- 103 silicon substrate
- 104 gate oxide layer
- 105 undoped polysilicon layer
- 106 photoresist
- 107 n-type implantation
- 110 layer sequence
- 111 n-doped polysilicon layer
- 112 hard mask
- 120 layer sequence
- 121 BARC structure
- 122 photoresist structure
- 130 layer sequence
- 131 hard mask structure
- 140 CMOS gate stack layer sequence
- 141 undoped gate
- 142 n-doped gate
- 200 p-MOS layer sequences
- 201 n-MOS layer sequences
- 202 layer sequences
- 203 silicon substrate
- 204 gate oxide layer
- 205 undoped polysilicon layer
- 206 photoresist
- 207 n-type implantation
- 210 layer sequences
- 211 n-doped polysilicon layer
- 212 hard mask
- 213 auxiliary undoped polysilicon layer
- 214 photoresist
- 215 n-type implantation

- 220 layer sequences
- 221 auxiliary n-doped polysilicon layer
- 222 BARC structure
- 223 photoresist structure
- 230 layer sequences
- 231 first laterally confined etching stack
- 232 second laterally confined etching stack
- 240 CMOS gate stack layer sequence
- 241 undoped gate
- 242 n-doped gate